

C0805X223J5GEC

ESD SMD Comm COG, Ceramic, 0.022 uF, 5%, 50 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.6 mm



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General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
T	1.1mm +/-0.10mm
S	0.6mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	Bulk, Bag
Packaging Quantity	1

Specifications

Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	45.4545 GOhms

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